

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. ADI contact information is listed below.

<b>PIN Title:</b>	Product Information Notice for Package Outline Drawing Change of Selected Products in SOIC Package
<b>Publication Date:</b>	26-Feb-2025
<b>Effectivity Date:</b>	26-Feb-2025 <i>(the earliest date that a customer could expect to receive changed material)</i>
<b>Revision Description:</b>	Initial Release.

#### Description Of Change:

Mold thickness, dimension A2, is being updated from 1.78 min - 2.03 max to 1.73 min - 1.78 max.



SIDE VIEW

#### Reason For Change:

This is a document correction only. Parts are compliant with EIA standards.

#### Impact of the change (positive or negative) on fit, form, function & reliability:

There is no impact to fit, form, function, quality, or reliability.

#### Summary of Supporting Information:

Revision will be shown in new Package Outline Drawing Rev E.

#### Comments:

THIS IS NOT A PCN. This is an advisory of correction to the Package Outline Drawing.

#### Supporting Documents:

#### ADI Contact Information:

For questions on this PIN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

**Appendix A - Impacted items, see csv PN listing in PCN Zip file**

**Appendix B – Revision History:**

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	26-Feb-2025	26-Feb-2025	Initial Release.